



## Material Content Data Sheet



Sales Product Name	BSB017N03LX3 G			Issued		19. November 2015		
MA#	MA000630354							
Package	MG-WDSO-2-8			Weight*		83.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.847	4.62	4.62	46174	46174
leadframe	non noble metal	copper	7440-50-8	74.415	89.33	89.33	893213	893213
leadfinish	non noble metal	nickel	7440-02-0	0.211	0.25		2535	
	noble metal	silver	7440-22-4	0.840	1.01	1.26	10083	12618
plating	non noble metal	nickel	7440-02-0	0.211	0.25	0.25	2535	2535
glue	plastics	epoxy resin	-	0.177	0.21		2125	
	noble metal	silver	7440-22-4	1.088	1.31	1.52	13054	15179
solder	non noble metal	copper	7440-50-8	0.011	0.01		132	
	noble metal	silver	7440-22-4	0.066	0.08		791	
	non noble metal	tin	7440-31-5	2.119	2.54	2.63	25429	26352
passivation	plastics	epoxy resin	-	0.327	0.39	0.39	3929	3929
*deviation	< 10%	Sum in total:			100.00			1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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